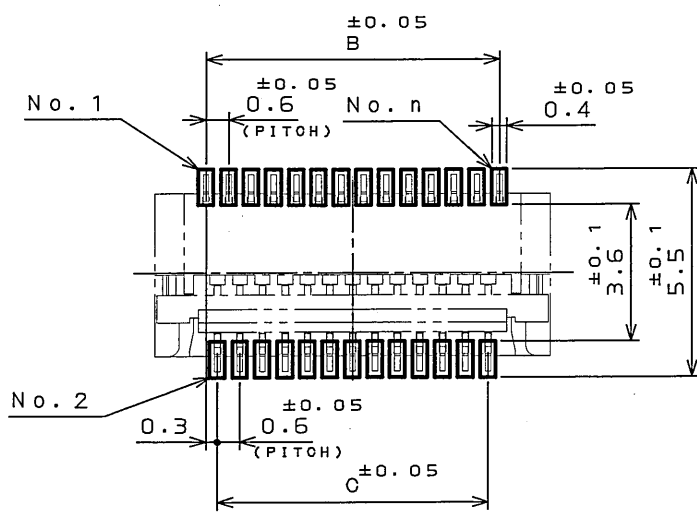
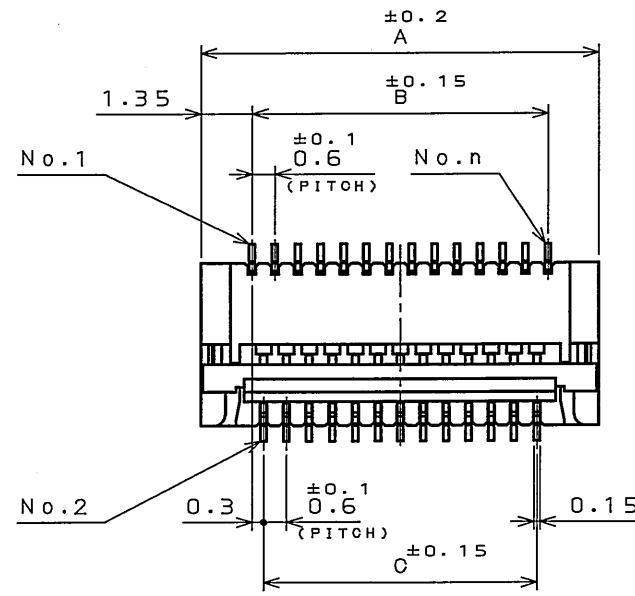
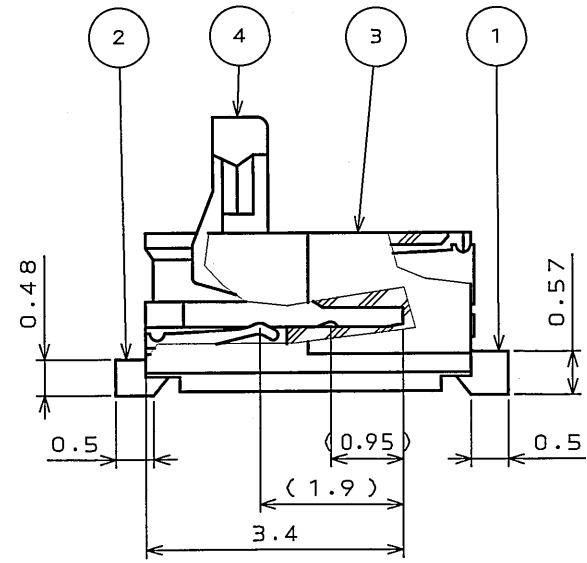
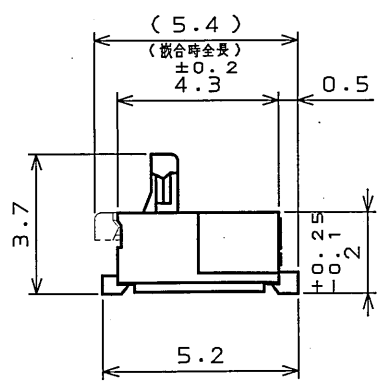
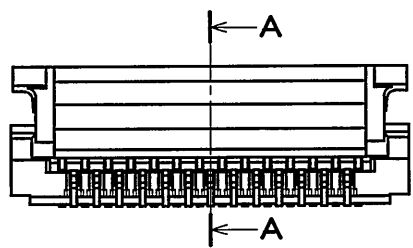


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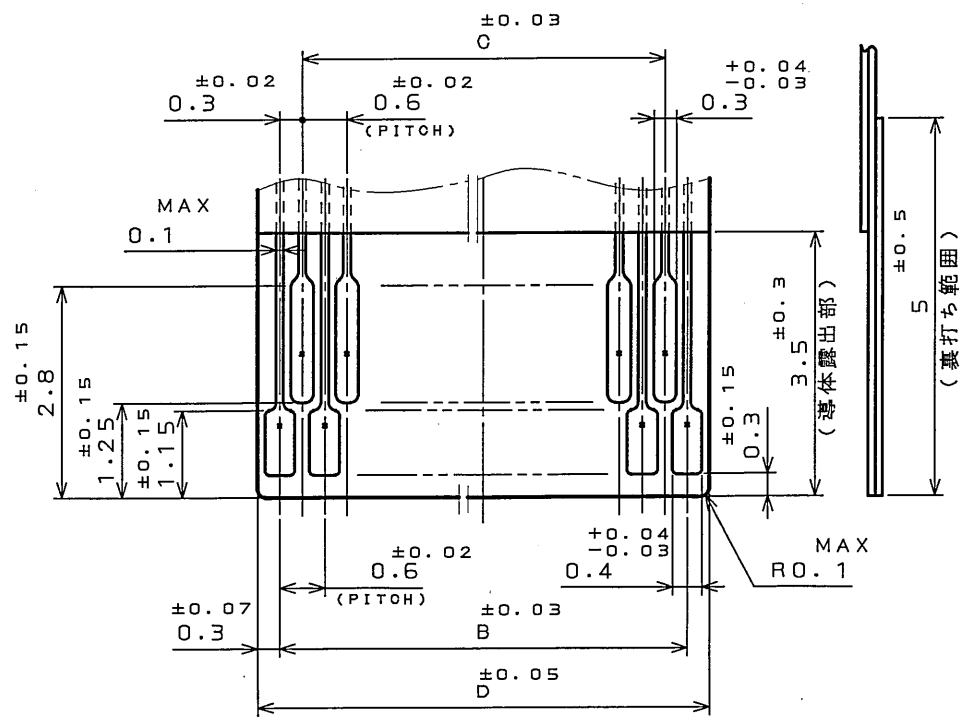
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	30.Mar.2001	47908	ADDED ITEM		N.IKENAGA		H.AMEMIYA
3	28.Mar.2002	49750	ADDED ITEM		N.IKENAGA	M.SUZUKI	T.MORINO
4	14.May.2002	49942	ADDED ITEM		N.IKENAGA	M.SUZUKI	T.MORINO
5	2.Dec.2003	053895	ADDED ITEM		N.IKENAGA		H.AMEMIYA



APPLICABLE P.C.B DIMENSION(REF.)
適合基板寸法(参考)



SECT. A-A
(SCALE 10:1)



(NOTE1)
APPLICABLE F.P.C DIMENSION(REF.)
適合FPC寸法(参考)

(THICKNESS : 0.2 ± 0.03)

NOTE1.POLYIMIDE SHOULD BE USED AS A REINFORCED BOARD AND THERMOSETTING ADHESIVE SHOULD BE USED.
BARE TRACES SHOULD BE GIVEN GOLD PLATING.

注1.適合FPCの補強板はホ'リイミド'を使用し、
接着剤は熱硬化性を使用すること。
又、仕上げは金メッキのこと。

TABLE 1

NO. OF CONTACT	A	B	C	D
17	7.5	4.8	4.2	5.4
△ 21	8.7	6	5.4	6.6
△ 25	9.9	7.2	6.6	7.8
△ 27	10.5	7.8	7.2	8.4
△ 33	12.3	9.6	9.0	10.2
△ 39	14.1	11.4	10.8	12
△ 45	15.9	13.2	12.6	13.8
△ 51	17.7	15	14.4	15.6
△ 57	19.5	16.8	16.2	17.4

4	SLIDER	1	GLASS FILLED PPS		COLOR : BROWN UL94V-0
3	BASE INSULATOR	1	GLASS FILLED LCP		COLOR : BEIGE UL94V-0
2	CONTACT 2	$\frac{n-1}{2}$	COPPER ALLOY	SELECTIVE GOLD PLATING	
1	CONTACT 1	$\frac{n+1}{2}$	COPPER ALLOY	GOLD PLATING	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS

仕様書(SPECIFICATION) JACS-1656 JAHL-1656		第1版(ORIGINAL DATE) 14.Feb.2001		尺規(SCALE) シリコン樹脂 5:1 IL-FHJ	
公差(GENERAL TOLERANCE)		製図 DR.		名称(TITLE) Reference Only	
寸法(DIMENSION)		担当 CHK. N.IKENAGA		JAVIATION ELECTRONICS INDUSTRY, LTD.	
角度(ANGLES)		査閲 APPD.		図面番号(DRAWING NO.)	
· ±0.8	° ±	承認 APPD. H.AMEMIYA		SJ035758	
·X ±0.4	°X ±	重量(WEIGHT)		版数(REV.)	
·XX ±0.1		JAE CONNECTOR GOM		5	
·XXX ±		JAE CONNECTOR GOM			

DOF-0-212D(98.02)

CDS-01-180-50065

SIZE A3